

**Amendments to the Claims:**

The listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1-8. (Canceled)

9. (Currently Amended) A method of conveying a substrate from a first base including a first substrate holding mechanism to a second base including a second substrate holding mechanism using a conveyor including a third substrate holding mechanism, the method comprising:

the conveyor attaching the third substrate holding mechanism ~~including a first substrate~~ including an electrostatic chuck ~~and a second fluid jetting mechanism~~ to the substrate with the first substrate holding mechanism holding the substrate;

driving the third substrate holding mechanism so as to hold the substrate by the ~~conveyor~~ electrostatic chuck attracting the substrate while the substrate is placed on the first base ~~is holding the substrate, and thereafter canceling the holding of the substrate by the first substrate holding mechanism;~~

the conveyor conveying the substrate from the first base to the second base and attaching the substrate to the second substrate holding mechanism; and

driving the second substrate holding mechanism so as to hold the substrate by the second base while the third substrate holding mechanism is ~~holding attached to the substrate, and thereafter jetting out fluid from the second fluid jetting mechanism and canceling the holding of the substrate by the third substrate holding mechanism.~~

10. (Canceled)

11. (Original) The method of conveying the substrate as claimed in claim 9, wherein the substrate is held by the first substrate holding mechanism after being subjected to backgrinding.

12. (Previously Presented) The method of conveying the substrate as claimed in claim 9, wherein:

at least one of the first and second bases and the conveyor are provided in reduced pressure chambers, and the substrate holding mechanism provided to the base provided in the reduced pressure chamber is an electrostatic chuck.

13. (Original) The method of conveying the substrate as claimed in claim 12, wherein:

in transferring the substrate between the substrate holding mechanism provided to the base provided in the reduced pressure chamber and the third

substrate holding mechanism, voltage is applied to the electrostatic chuck from which the substrate is transferred so that an electrostatic force is generated in a direction to separate the substrate therefrom.